

CLAIMS

1. A wafer protective sheet comprising a synthetic resin sheet with a thickness of 80 to 130 μm having a large number of projected parts and a large number of recessed parts on the respective front surface and rear surface thereof, wherein the large number of projected parts and the large number of recessed parts are respectively so disposed that each part is positioned at intersections of lattice stripes, and the projected part and the recessed part are disposed alternately each other; the sheet has such a wavy cross section that the recessed parts in the rear surface match the projected parts on the front surface and the projected parts on the rear surface match the recessed parts in the front surface; and the wafer protective sheet has a bending resistance of 30 to 80 mm.
2. The wafer protective sheet according to Claim 1, wherein the wafer protective sheet is formed of a synthetic resin compound having a flexural modulus of 1.0×10^3 to 1.2×10^3 MPa.
3. The wafer protective sheet according to Claim 1, wherein the height of the projected parts and recessed parts is 20 to 50 μm .
4. The wafer protective sheet according to Claim 1, wherein the density of the projected parts and recessed parts, that is, the number of projected parts per area and/or the number of recessed parts per sheet area, is 0.5 to 16 per square centimeter.
5. The wafer protective sheet according to Claim 1, wherein the synthetic resin

contains an antistatic agent to exhibit an antistatic property.

6. The wafer protective sheet according to Claim 5, wherein the wafer protective sheet has a surface resistivity of $10^{12} \Omega$ or less.

7. The wafer protective sheet according to Claim 1, wherein the wafer protective sheet has flat parts in addition to the projected parts and the recessed parts.

8. The wafer protective sheet according to Claim 7, wherein the flat parts occupy 60% or more of the total area of the front and rear surfaces of the wafer protective sheet.